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Remember to give due consideration to safety when making your circuit designs, with appropriate
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2SB1392

Silicon PNP Triple Diffused



ADE-208-872 (Z) 1st. Edition September 2000

Application

Low frequency power amplifier

Outline

TO-220FM



- 1. Base
- 2. Collector
- 3. Emitter

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit	
Collector to base voltage	V_{CBO}	– 70	V	
Collector to emitter voltage	V _{CEO}	-60	V	
Emitter to base voltage	V_{EBO}	- 5	V	
Collector current	I _c	-4	A	
Collector peak current	I _{C(peak)}	-8	A	
Collector power dissipation	P _c	2	W	
	P _c *1	25		
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. Value at $T_c = 25$ °C.

2SB1392

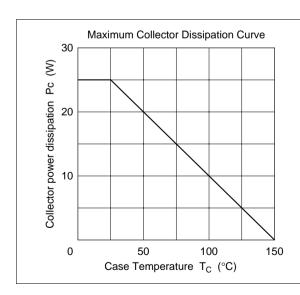
Electrical Characteristics ($Ta = 25^{\circ}C$)

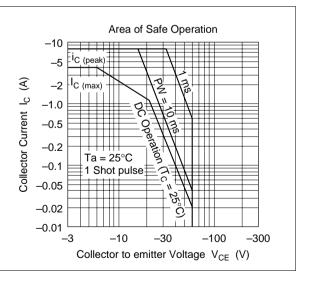
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	–7 0	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-60	_	_	V	$I_{C} = -50 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \mu A, I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-10	μΑ	$V_{CB} = -50 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	-10		$V_{CE} = -50 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h _{FE1} *2	60	_	200		$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}^{*1}$
	h _{FE2}	35	_	_		$V_{CE} = -4 \text{ V}, I_{C} = -0.1 \text{ A}^{*1}$
Base to emitter voltage	V_{BE}	_	_	-1.0	V	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1.0	V	$I_{\rm C} = -2.0 \text{ A}, I_{\rm B} = -0.2 \text{ A}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)}$	_	_	-1.2	V	$I_{\rm C} = -2.0 \text{ A}, I_{\rm B} = -0.2 \text{ A}^{*1}$

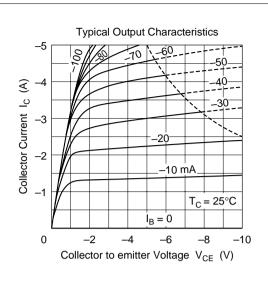
Notes: 1. Pulse test.

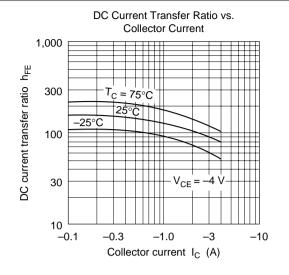
2. The 2SB1392 is grouped by $h_{\mbox{\tiny FE1}}$ as follows.

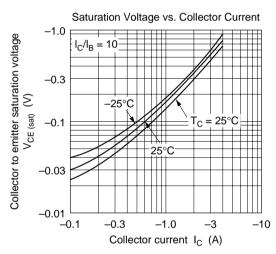
В	С
60 to 120	100 to 200

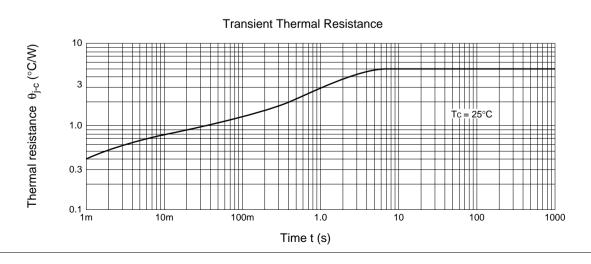












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